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DIALOG(R)File 351:Derwent WPI
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Microcapsule enclosing amine cpd. - obtd. by mixing amine cpd. and hydrophobic soln. in organic soln. dispersing in aq. medium and heating

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Number of Countries: 001 Number of Patents: 002

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 6126153	A	19940510	JP 92280223	A	19921019	199423 B
JP 3411049	B2	20030526	JP 92280223	A	19921019	200335

Priority Applications (No Type Date): JP 92280223 A 19921019

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
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JP 6126153	A	8	B01J-013/06		
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JP 3411049	B2	7	B01J-013/06	Previous Publ. patent JP 6126153	
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Abstract (Basic): JP 6126153 A

Microcapsule (C) comprises: (C1) protective wall material and (C2) and amine-cpd. in an amt. of 45-80 wt.% enclosed in (C1) wall material. Thickness of (C1) wall is 3-10% of dia. of (C)microcapsule.

Pref. (C1) wall material is of PMMA, polystyrene, copolymer of ethylene/vinyl-acetate, polyvinyl-toluene, etc.; of which MW is 1600-100000. Pref. (C2) amine-cpd. is an aliphatic or aromatic polyamine. Prepn. of (C) microcapsule comprises mixing (C2) amine-cpd. and (C1) a hydrophobic soln. of (C1) material in (S) an organic solvent, dispersing into an aq. medium with an emulsifier and heating.

(S) organic solvent is pref. acetic acid ester or chlorine-cpd..

(C2) amine-cpd. is pref. penta-ethylene-hexamine, triethylene-tetramine, tetra-ethylene-pentamine. etc..

USE/ADVANTAGE - Microcapsule enclosing an amine-cpd. is used for adhesive used together with, e.g. bis-phenol-A-epoxy-resin, etc.; and has a high concn. of enclosed amine and a high strength of wall material which can be easily produced without making aq. soln. of the amine.

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Derwent Class: A18; A81; G03; J04

International Patent Class (Main): B01J-013/06

International Patent Class (Additional): C08G-059/40; C08G-059/50; C08J-003/12; C09J-163/00